

**/ Descriptions**

KF \$) )' = E GE Silicon NPN transistor in a TO-220F Plastic Package.

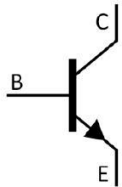
**/ Features**

# #G: 4 \*' N #  
Low  $V_{CE(sat)}$ , excellent DC current gain characteristics,  $P_C=30W$ , wide SOA.

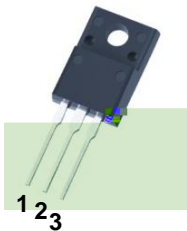
**/ Applications**

General Purpose Power Amplifier.

**/ Equivalent Circuit**



**/ Pinning**



PIN1 Base      PIN 2 Collector      PIN 3 Emitter

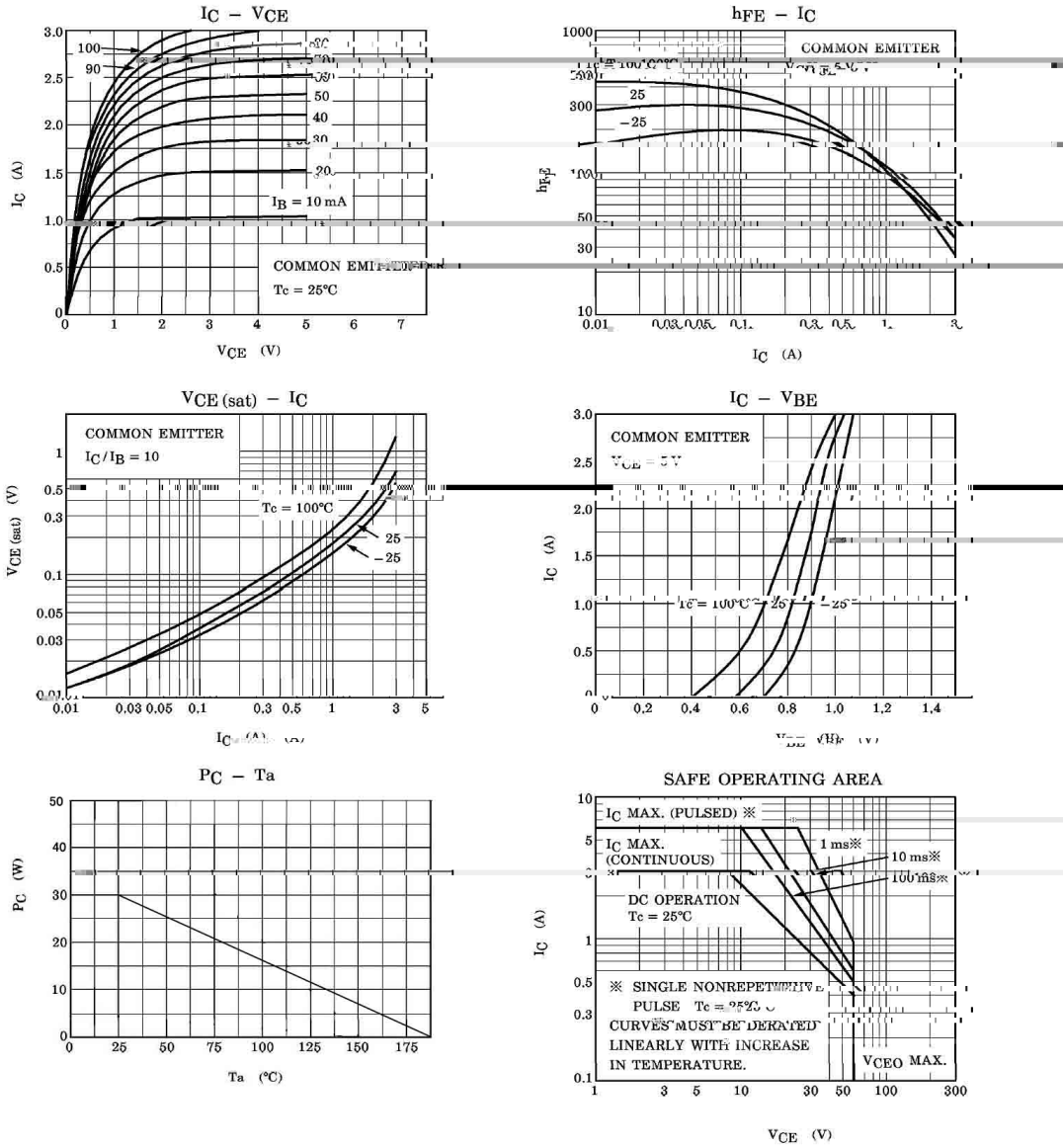
**/  $h_{FE}$  Classifications & Marking**

$h_{FE}$ Classifications Symbol	E	F
$h_{FE}$ Range	100 200	160 320

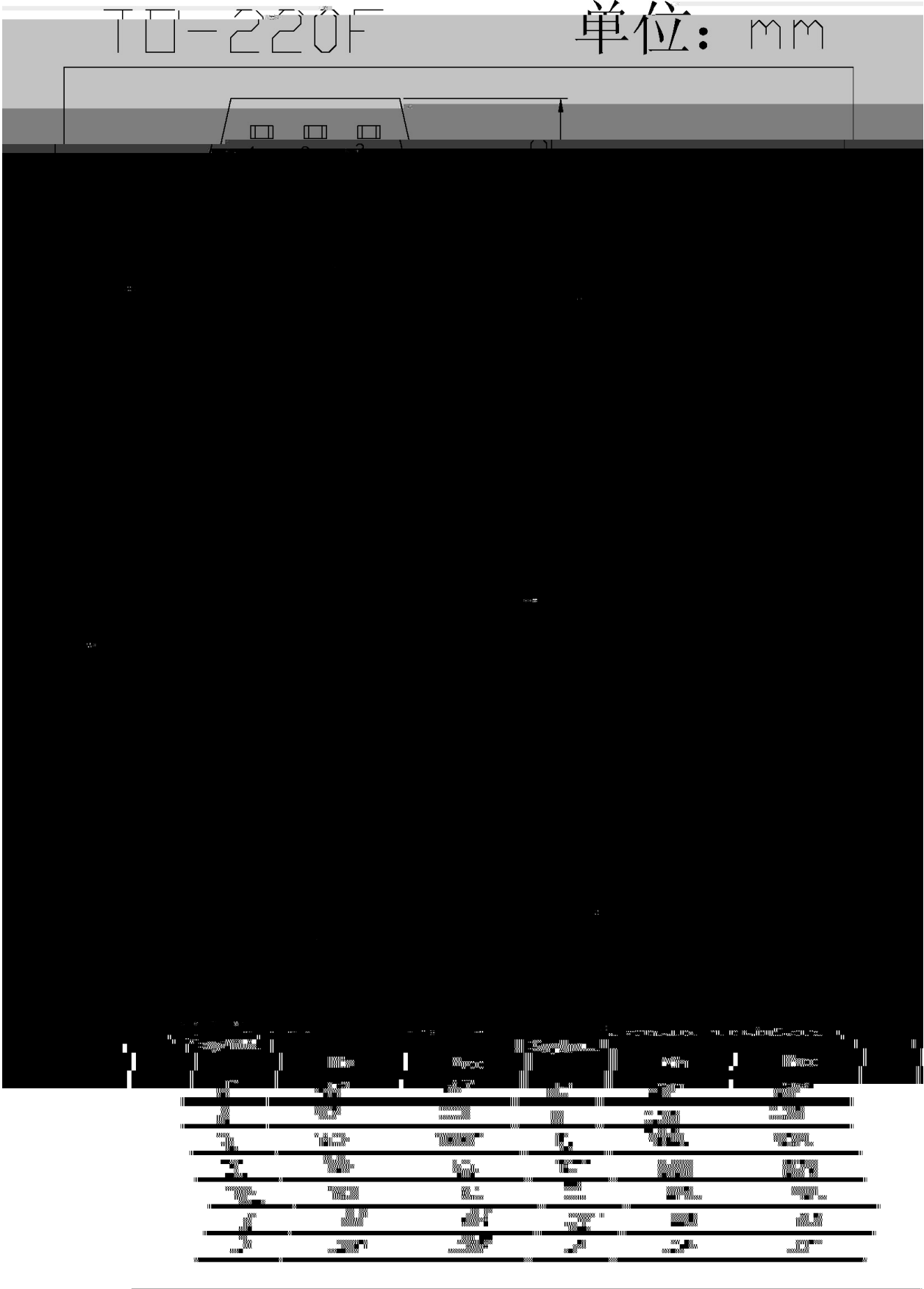
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	$V_{CBO}$	80	V
Collector to Emitter Voltage	$V_{CEO}$	60	V
Emitter to Base Voltage	$V_{EBO}$	5.0	V
Collector Current - Continuous	$I_C$	3.0	A
Peak Collector Current	$I_{CM}$	6.0	A
Collector Power Dissipation	$P_C$	2.0	W
Collector Power Dissipation	$P_C(T_c=25^\circ C)$	30	W
Junction Temperature	$T_j$	150	
Storage Temperature Range	$T_{stg}$	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	$V_{CBO}$	$I_C=50\text{ A}$	80			V
Collector to Emitter Breakdown Voltage	$V_{CEO}$	$I_C=1.0\text{mA}$	60			V
Emitter to Base Breakdown Voltage	$V_{EBO}$	$I_E=50\text{ A}$	5.0			V
Collector Cut-Off Current	$I_{CBO}$	$V_{CB}=60\text{V}$ $I_E=0$			10	A
Emitter Cut-Off Current	$I_{EBO}$	$V_{EB}=4.0\text{V}$ $I_C=0$			10	A
DC Current Gain	$h_{FE}$	$V_{CE}=5.0\text{V}$ $I_C=500\text{mA}$	100		320	

/ Electrical Characteristic Curve



/ Package Dimensions



**2SD2061**  
Rev.E Mar.-20

DATA SHEET

( ) / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- |   |        |     |            |        |                                           |
|---|--------|-----|------------|--------|-------------------------------------------|
| 1 | 25     | 150 | 60         | 90sec; | 1.Preheating:25~150 , Time:60~90sec.      |
| 2 | 255..5 |     | 5..0.5sec; |        | 2.Peak Temp.:255..5 , Duration:5..0.5sec. |
| 3 |        | 2   | 10         | /sec.  | 3. Cooling Speed: 2~10 /sec.              |

/ Resistance to Soldering Heat Test Conditions

270..5                      10..1 sec.                      Temp.:270±5                      Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units					Dimension (unit mm <sup>3</sup> )		
	Units/Bag /	Bags/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Bag	Inner Box	Outer Box
TO-220/F	200	10	2,000	5	10,000	135×190	237×172×102	560×245×195